

BYW32GP THRU BYW36GP

SINTERED GLASS JUNCTION
FAST SWITCHING PLASTIC RECTIFIER
VOLTAGE:200 TO 600V **CURRENT: 2.0A**



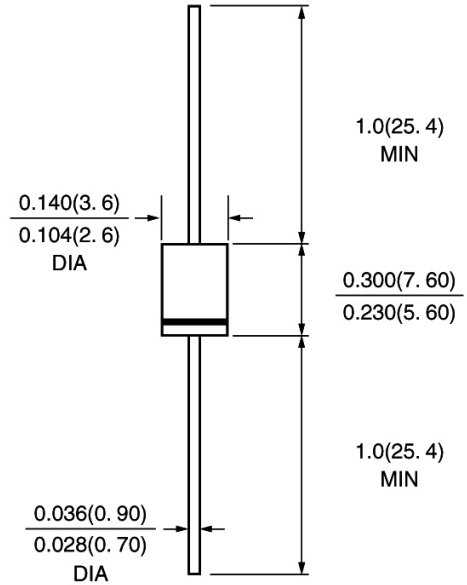
FEATURE

High temperature metallurgically bonded construction
 Sintered glass cavity free junction
 Capability of meeting environmental standard of MIL-S-19500
 High temperature soldering guaranteed
 350°C /10sec/0.375"lead length at 5 lbs tension
 Operate at Ta =55°C with no thermal run away
 Typical Ir<0.1µA

MECHANICAL DATA

Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C
 Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy
 Polarity: color band denotes cathode
 Mounting position: any

DO-15DO-204C



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

	SYMBOL	BYW 32GP	BYW 33GP	BYW 34GP	BYW 35GP	BYW 36GP	units
Maximum Recurrent Peak Reverse Voltage	Vrrm	200	300	400	500	600	V
Maximum RMS Voltage	Vrms	140	210	280	350	420	V
Maximum DC blocking Voltage	Vdc	200	300	400	500	600	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =45°C	If(av)	2.0					A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	Ifsm	50					A
Maximum Forward Voltage at rated Forward Current and 25°C at 1.0A	Vf	1.1					V
Non-repetitive peak reverse avalanche energy (Note 1)	Ersm	10					mJ
Maximum DC Reverse Current Ta =25°C at rated DC blocking voltage Ta =125°C	Ir	5.0 150					µA µA
Maximum Reverse Recovery Time (Note 2)	Trr	200					nS
Typical Junction Capacitance (Note 3)	Cj	60					pF
Typical Thermal Resistance (Note 4)	R(ja)	20					°C /W
Storage and Operating Junction Temperature	Tstg, Tj	-65 to +175					°C

Note: 1.R=400mA; Tj=Tjmax prior to surge; inductive load switched off
 2.Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A
 3.Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
 4.Thermal Resistance from Junction to Ambient at 3/8"lead length, P.C. Board Mounted

Figure 1. Max. Thermal Resistance vs. Lead Length

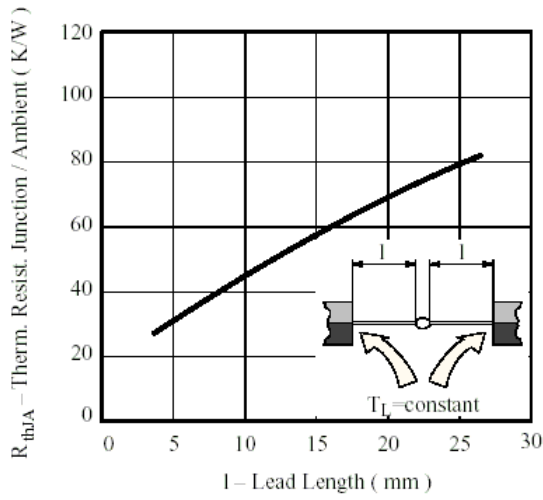


Figure 2. Reverse Current vs. Junction Temperature

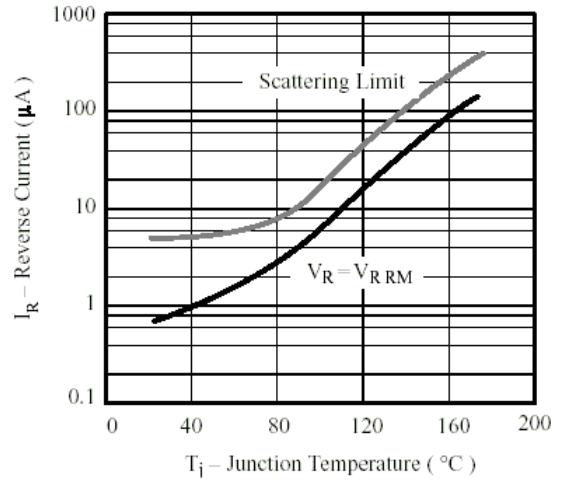


Figure 3. Max. Average Forward Current vs. Ambient Temperature

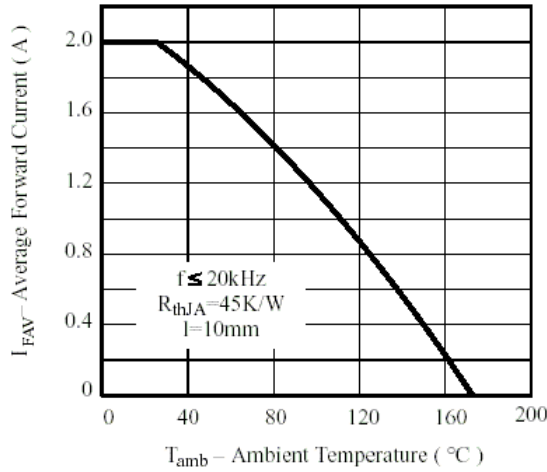


Figure 4. Max. Forward Current vs. Forward Voltage

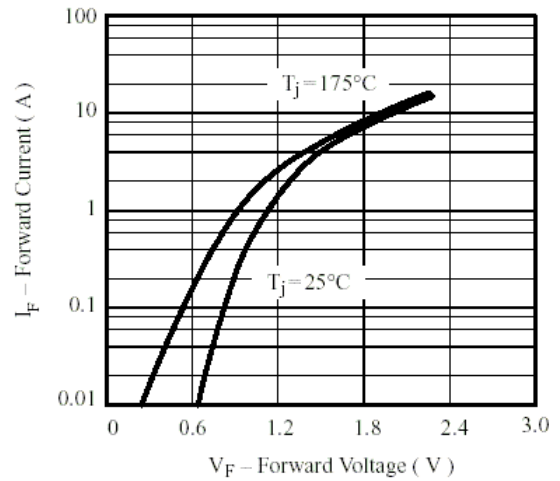


Figure 5. Typ. Diode Capacitance vs. Reverse Voltage

